

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT6457225

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
WILLIAM A. LENDVAY	09/24/2018
RECEIVING PARTY DATA	
Name:	MICRON TECHNOLOGY, INC.
Street Address:	8000 SOUTH FEDERAL WAY
City:	BOISE
State/Country:	IDAHO
Postal Code:	83716-9632
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17125788
CORRESPONDENCE DATA	
Fax Number:	(612)659-9344
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	612-659-9340
Email:	sherar@bipl.net
Correspondent Name:	BROOKS, CAMERON & HUEBSCH, PLLC
Address Line 1:	1201 MARQUETTE AVENUE SOUTH
Address Line 2:	SUITE 400
Address Line 4:	MINNEAPOLIS, MINNESOTA 55403
ATTORNEY DOCKET NUMBER:	1002.2800002[18-017701US]
NAME OF SUBMITTER:	BJORN A. JOHNSON
SIGNATURE:	/Bjorn A. Johnson/
DATE SIGNED:	12/17/2020
Total Attachments: 2	
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**In re Application of:
William A. Lendvay**

Docket No. 1002.2800001

Disclosure No. 2018-0177.00/US

Filed: Concurrently Herewith

For : ISOLATION COMPONENT

ASSIGNMENT

FOR GOOD AND VALUABLE CONSIDERATION, the receipt, sufficiency and adequacy of which are hereby acknowledged, the undersigned does hereby:

SELL, ASSIGN, AND TRANSFER TO **Micron Technology, Inc.** (the "Assignee"), a corporation of Delaware, having a place of business at 8000 South Federal Way, Boise, Idaho 83716-9632, the entire right, title, and interest for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned concurrently herewith and is entitled "ISOLATION COMPONENT"; such application and all divisional, continuing, substitute, renewal, reissue and all other applications for patent which have been or shall be filed in the United States and all foreign countries on any of such improvements; all original and reissued patents which have been or shall be issued in the United States and all foreign countries on such improvements; and specifically including the right to file foreign applications under the provisions of any convention or treaty and claim priority based on such application in the United States of America;

AUTHORIZE AND REQUEST the issuing authority to issue any and all United States and foreign patents granted on such improvements to the Assignee;

WARRANT AND COVENANT that no assignment, grant mortgage, license, or other agreement affecting the right and property herein conveyed has been or will be made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned;

COVENANT that, when requested and at the expense of the Assignee, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all such improvements; execute all rightful oaths, declarations, assignments, powers of attorney, and other papers; communicate to the Assignee all facts known to the undersigned relating to such improvements and the history thereof; and generally do everything possible which the Assignee shall consider desirable for securing, maintaining, and enforcing proper patent protection for such improvements and for vesting title to such improvement in the Assignee;

TO BE BINDING on the heirs, assigns, representatives, and successors of the undersigned and extend to the successors, assigns, and nominees of the Assignee.

IN TESTIMONY WHEREOF, I have hereunto set my hand this 24 day of September, 2018.


William A. Lendvay

Date: Sept 24, 2018